

Power MOS Field-Effect Transistors

N-Channel Enhancement-Mode Power Field-Effect Transistors

4 A, 350 V and 400 V

$r_{DS(on)}$: 2Ω

Features:

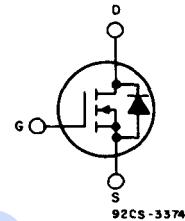
- SOA is power-dissipation limited
 - Nanosecond switching speeds
 - Linear transfer characteristics
 - High input impedance
 - Majority carrier device

The RFM4N35 and RFM4N40 and the RFP4N35 and RFP4N40^{*} are n-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

The RFM-series types are supplied in the JEDEC TO-204AA steel package and the RFP-series types in the JEDEC TO-220AB plastic package.

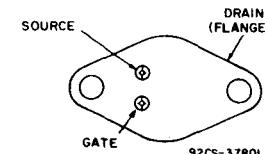
*The RFM and RFP series were formerly RCA developmental numbers TA9393 and TA9394, respectively.

TERMINAL DIAGRAM



N-CHANNEL ENHANCEMENT MODE

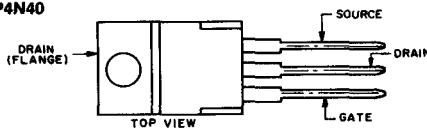
TERMINAL DESIGNATIONS



**RFM4N35
RFM4N40**

400

RFP4N35
RFP4N16



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MAXIMUM RATINGS. Absolute-Maximum Values ($T_C=25^\circ C$):

	RFM4N35	RFM4N40	RFP4N35	RFP4N40	
DRAIN-SOURCE VOLTAGE	V_{DSS}	350	400	350	400
DRAIN-GATE VOLTAGE ($R_g=1\text{ M}\Omega$) ...	V_{DGR}	350	400	350	400
GATE-SOURCE VOLTAGE	V_{GS}			± 20	
DRAIN CURRENT, RMS Continuous	I_D			4	
Pulsed	I_{DM}			8	
POWER DISSIPATION @ $T_c=25^\circ\text{C}$	P_T	7.5	7.5	60	60
Derate above $T_c=25^\circ\text{C}$		0.6	0.6	0.48	0.48
OPERATING AND STORAGE TEMPERATURE	T_J , T_{SJQ}			-55 to +150	$^\circ\text{C}$

RFM4N35, RFM4N40, RFP4N35, RFP4N40ELECTRICAL CHARACTERISTICS, At Case Temperature (T_c) 25°C unless otherwise specified.

CHARACTERISTICS	SYMBOL	TEST CONDITIONS	LIMITS				UNITS	
			RFM4N35 RFP4N35		RFM4N40 RFP4N40			
			MIN.	MAX.	MIN.	MAX.		
Drain-Source Breakdown Voltage	V_{DSS}	$I_D=1\text{ mA}$ $V_{GS}=0$	350	—	400	—	V	
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{GS}=V_{DS}$ $I_D=1\text{ mA}$	2	4	2	4	V	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=280\text{ V}$ $V_{DS}=320\text{ V}$	—	10	—	—	μA	
		$T_c=125^\circ\text{C}$ $V_{DS}=280\text{ V}$ $V_{DS}=320\text{ V}$	—	100	—	—		
Gate-Source Leakage Current	I_{GS}	$V_{GS}=\pm 20\text{ V}$ $V_{DS}=0$	—	100	—	100	nA	
Drain-Source On Voltage	$V_{DS(\text{on})}^a$	$I_D=2\text{ A}$ $V_{GS}=10\text{ V}$	—	4	—	4	V	
		$I_D=4\text{ A}$ $V_{GS}=10\text{ V}$	—	12	—	12		
Static Drain-Source On Resistance	$r_{DS(\text{on})}^a$	$I_D=2\text{ A}$ $V_{GS}=10\text{ V}$	—	2	—	2	Ω	
Forward Transconductance	g_{fss}^a	$V_{DS}=10\text{ V}$ $I_D=2\text{ A}$	1	—	1	—	mho	
Input Capacitance	C_{iss}	$V_{DS}=25\text{ V}$	—	750	—	750	pF	
Output Capacitance	C_{oss}	$V_{GS}=0\text{ V}$	—	150	—	150		
Reverse Transfer Capacitance	C_{iss}	$f=1\text{ MHz}$	—	100	—	100		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD}=200\text{ V}$	12(typ)	45	12(typ)	45	ns	
Rise Time	t_r	$I_D=2\text{ A}$	42(typ)	60	42(typ)	60		
Turn-Off Delay Time	$t_{d(\text{off})}$	$R_{gen}=R_{gs}=50\Omega$	130(typ)	200	130(typ)	200		
Fall Time	t_f	$V_{GS}=10\text{ V}$	62(typ)	100	62(typ)	100		
Thermal Resistance Junction-to-Case	$R_{\theta_{JC}}$	RFM4N35, RFM4N40	—	1.67	—	1.67	$^\circ\text{C/W}$	
		RFP4N35, RFP4N40	—	2.083	—	2.083		

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SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS

CHARACTERISTIC	SYMBOL	TEST CONDITIONS	LIMITS				UNITS	
			RFM4N35 RFP4N35		RFM4N40 RFP4N40			
			MIN.	MAX.	MIN.	MAX.		
Diode Forward Voltage	V_{SD}^a	$I_{SD}=2\text{ A}$	—	1.4	—	1.4	V	
Reverse Recovery Time	t_r	$I_F=4\text{ A}$ $d_I/dt=100\text{ A}/\mu\text{s}$	800(typ)		800(typ)		ns	

^aPulsed: Pulse duration = 300 μs max., duty cycle = 2%

RFM4N35, RFM4N40, RFP4N35, RFP4N40

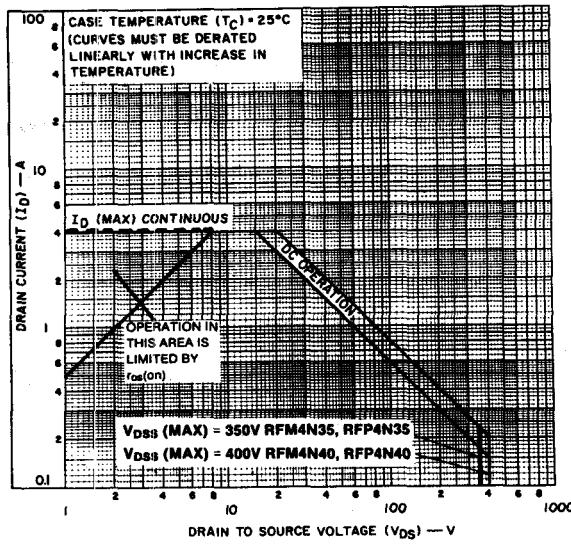


Fig. 1 — Maximum operating areas for all types.

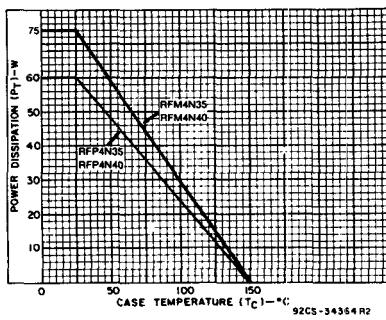


Fig. 2 — Power dissipation vs. temperature derating curve for all types.

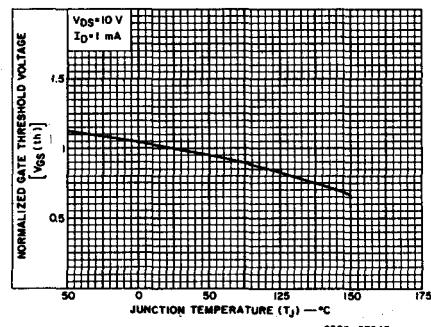


Fig. 3 — Typical normalized gate threshold voltage as a function of junction temperature for all types.

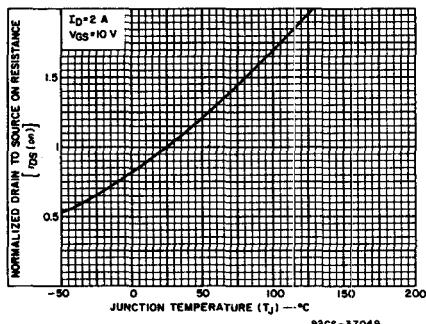


Fig. 4 — Normalized drain-to-source on resistance to junction temperature for all types.

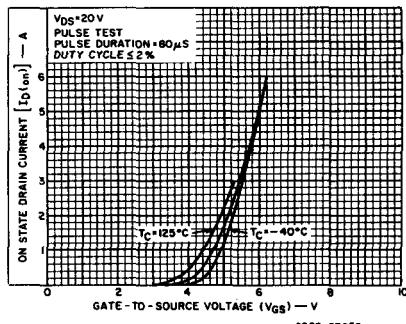


Fig. 5 — Typical transfer characteristics for all types.

RFM4N35, RFM4N40, RFP4N35, RFP4N40

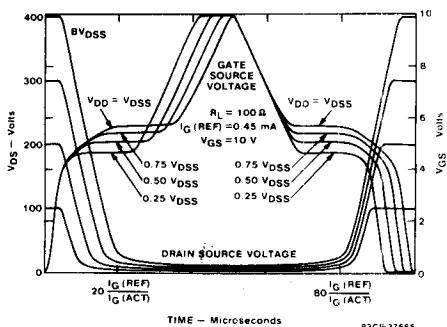


Fig. 6 - Normalized switching waveforms for constant gate-current.
Refer to RCA application notes AN-7254 and AN-7260.

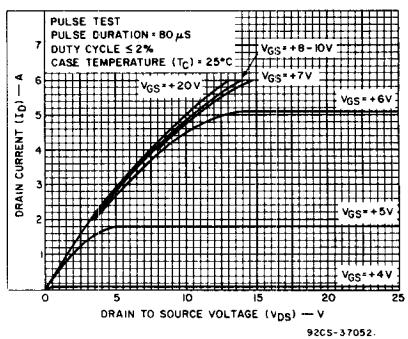


Fig. 7 — Typical saturation characteristics for all types.

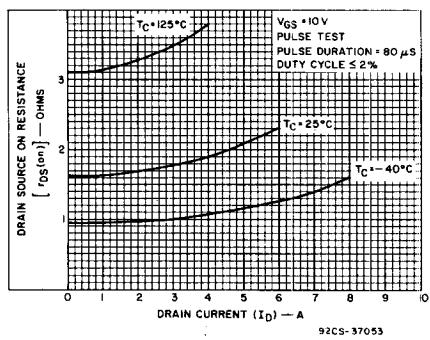


Fig. 8 — Typical drain-to-source on resistance as a function of drain current for all types.

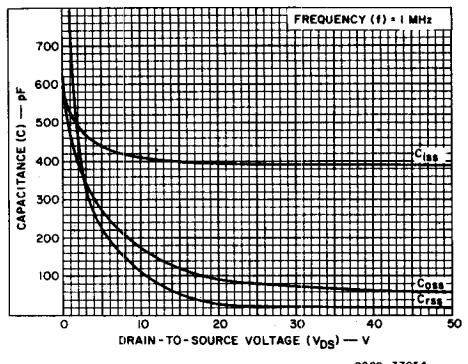


Fig. 9 — Capacitance as a function of drain-to-source voltage for all types.

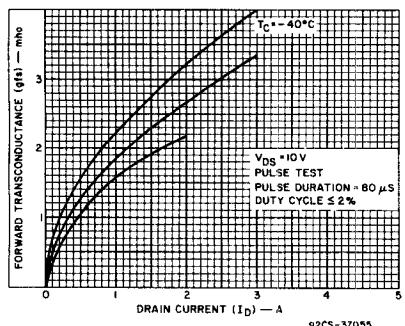


Fig. 10 — Typical forward transconductance as a function of drain current for all types.

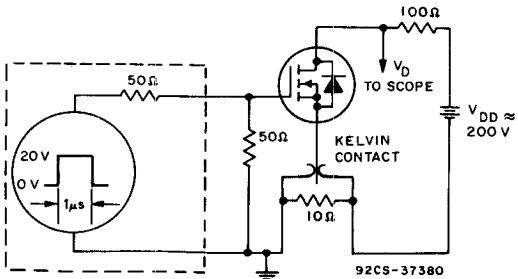


Fig. 11 — Switching Time Test Circuit